

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	22	"6576992"	US-PGPUB; USPAT	OR	ON	2005/04/19 10:05
L4	5321	(edge near2 pad) and (ic or "integrated circuit" or chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/19 11:02
L5	1512	("edge pad") and (ic or "integrated circuit" or chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/19 11:02
L6	282	("edge pad") and (ic or "integrated circuit" or chip) and stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/19 11:04
L7	156	("edge pad") and (ic or "integrated circuit" or chip) and stack\$3 and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/19 11:15
L8	144	("edge pad") and ("area array" or csp or "chip scale package" or bga or "ball grid array")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/19 11:16
L9	120	("edge pad") and ("area array" or bga or "ball grid array")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/19 11:16
S1	1809	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/18 11:14
S3	727	(438/109).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/18 12:45

S4	494	"area array" and cable and (ic or integrated near2 circuit or chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 12:47
S5	234	"area array" and cable and (ic or integrated near2 circuit or chip) and stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 12:47
S7	386	(terminal or ball) near2 pad and (connect\$3 near2 pad) and staggered	US-PGPUB; USPAT	OR	ON	2005/04/18 16:40
S8	153	(terminal or ball) near2 pad and (connect\$3 near2 pad) and staggered and straight	US-PGPUB; USPAT	OR	ON	2005/04/18 14:43
S9	320	flex\$4 near2 circuit and (mcm or multi near2 chip) and stacked	US-PGPUB; USPAT	OR	ON	2005/04/18 14:53
S10	346	flex\$4 near2 (circuit or pcb or printed) and (mcm or multi near2 chip) and stacked	US-PGPUB; USPAT	OR	ON	2005/04/18 15:51
S14	63	"Lee, Dong-Ho".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:28
S15	107	flex\$4 near2 (circuit or pcb or printed) and (mcm or multi near2 chip) and stacked and (bga or ball near2 grid near2 array)	US-PGPUB; USPAT	OR	ON	2005/04/18 16:03
S16	875	flex\$4 near2 (circuit or pcb or printed or pwb) and (mcm or multi near2 chip) and substrate	US-PGPUB; USPAT	OR	ON	2005/04/18 16:26
S17	13	flex\$4 near2 (circuit or pcb or printed or pwb) and (mcm or multi near2 chip) and substrate and (terminal or ball) near2 pad and (connect\$3 near2 pad) and staggered	US-PGPUB; USPAT	OR	ON	2005/04/18 16:27
S18	70	flex\$4 near2 (circuit or pcb or printed or pwb) and (terminal or ball) near2 pad and (connect\$3 near2 pad) and staggered and wiring	US-PGPUB; USPAT	OR	ON	2005/04/18 16:51

S19	18	("5159535" "5450283" "5578525" "5646446" "5773882" "5783870" "5949142" "5969426" "6071755" "6075287" "6208521" "6324067").PN. OR ("6486544").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/18 16:33
S20	17	("5483024" "5583375" "5939779" "6002167" "6080931" "6087718").PN. OR ("6177721").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/18 16:35
S24	2	("6576992").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/18 16:38
S26	41	(terminal or ball) near2 pad and (connect\$3 near2 pad) and staggered and (mcm or multi near2 chip) and stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 16:43
S27	49	(terminal or ball) near2 pad and (connecting near2 pad) and staggered and stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 16:45
S28	25	(terminal or ball) near2 pad and (connecting near2 pad) and staggered and (csp or chip near2 scale near2 package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 16:48
S29	1195	flex\$4 near2 (circuit or substrate or cable or wir\$3 or structure or rigid) and substrate and (chip or ic or "integrated circuit") and (terminal near2 pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 16:54
S30	456	flex\$4 near2 (circuit or substrate or cable or wir\$3 or structure or rigid) and substrate and (chip or ic or "integrated circuit") and (terminal near2 pad) and stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 16:54